

Flip-Chip Technologies World Market Segmentation, Major Key Players, Analysis and Forecast to 2022

Global Flip-Chip Technologies market is poised to reach \$57.04 billion by 2022, Compound Annual Growth Rate (CAGR) of 11.94% during the forecast period

PUNE, INDIA, September 2, 2016 /EINPresswire.com/ -- According to researcher, the Global [Flip-Chip Technologies](#) market is estimated at \$25.89 billion in 2015 and is poised to reach \$57.04 billion by 2022, growing at a Compound Annual Growth Rate (CAGR) of 11.94% during the forecast period. Flip chip is a key technology for advanced packaging of microelectronic circuits and other micro-devices. This technology is used to interconnect semiconductor IC with other ICs, peripheral circuits or substrate in efficient way by solving the heat transfer problem of semiconductor devices, improving performance at higher frequency and reducing the power consumption. Wide range of low-end and high-end electronic products, enhanced electrical performance and high interconnection density are the major factors favoring the market growth.

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Due to a global trend on banning the toxic material lead in electronic products, conventional flip chip assembly using lead-based solder bumps is facing a great challenge. Flip chip technology continues to advance and is playing a huge role in 2.5D interposers and 3DICs. The demand for copper pillars and microbumps are reshaping the Flip chip technology, which are swiftly becoming the innovative conventional bumping metallurgy solutions for die interconnections. Intel is the leading producer of flip chip. It is estimated that, by the year 2017 more than half of all bumped wafers for flip chips will be made with copper pillars.

Some of the key players in the global market include IBM Corp., Samsung Electronics Co. Ltd., Texas Instruments Inc., Amkor Technology Inc., Intel Corp., Taiwan Semiconductor Manufacturing Co., Global Foundries U.S. Inc., Powertech Technology Inc. and Advanced Semiconductor Engineering Inc, Nepes Pte. Ltd., Stmicroelectronics NV (STM) and Stats Chippac Ltd.

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Wafer Bumping Process Covered:

- Copper (Cu) pillar
- Tin-lead eutectic solder
- Lead free solder
- Gold stud and plated

End Use Covered:

- Medical devices
- Industrial applications
- Robotics
- Smartphones
- Desktop CPUs
- Laptops
- Automotive
- GPUs and chipsets
- Smart technologies
- Other computing devices

Applications Covered:

- Memory
- 2D logic system-on-a-chip (SoC)
- Imaging
- High-brightness light-emitting diode (HB-LED)
- RF, power and Analog ICs
- 2.5D/3D system-in-package/system-on-a-chip (SiP/SoC)

What our report offers:

- Market share assessments for the regional and country level segments
- Market share analysis of the top industry players
- Strategic recommendations for the new entrants
- Market forecasts for a minimum of 7 years of all the mentioned segments, sub segments and the regional markets
- Market Trends (Drivers, Constraints, Opportunities, Threats, Challenges, Investment Opportunities, and recommendations)
- Strategic recommendations in key business segments based on the market estimations
- Competitive landscaping mapping the key common trends
- Company profiling with detailed strategies, financials, and recent developments
- Supply chain trends mapping the latest technological advancements

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